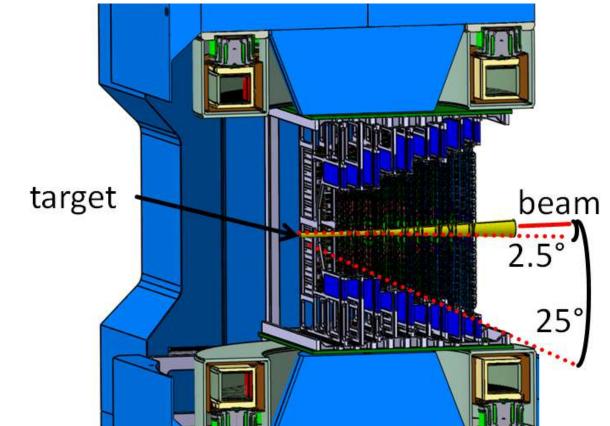
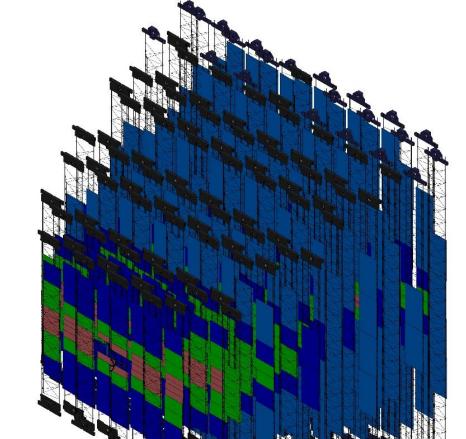
**CB** 

# Module and ladder assembly techniques for the Silicon Tracking System (STS) of the CBM experiment at FAIR Shaifali Mehta, for the CBM collaboration

Eberhard Karls Universität Tübingen, Tübingen, Germany

### **STS for the CBM Experiment**





# Ladder and detector modules

- 8 tracking stations • 106 Carbon fiber ladders
  - 896 detector modules
  - 8-10 modules on each ladder
  - Front end electronics at both ends of the ladder
  - Goal: Positioning of sensors in 3D



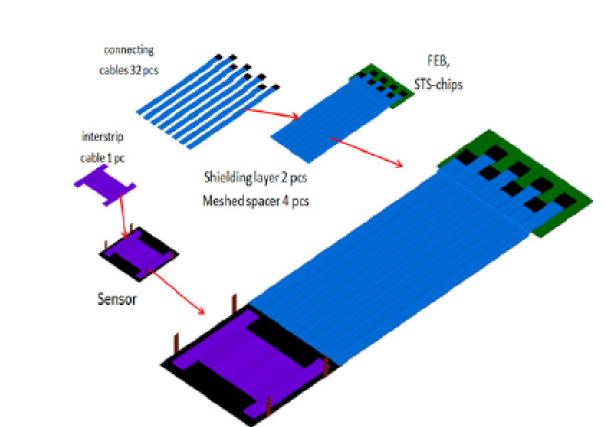
**Fig: STS inside the dipole** magnet



**Fig: STS with sensors mounted** 

on carbon fibre ladder

#### within order of 100 $\mu$ m



- Double-sided silicon
- micro-strip sensors
- Stereo angle 7.5°
- 58 µm pitch
- 1024 strips on each side
- Strip length: 2/4/6/12 cm
- Strip width: 6 cm

## **Module assembly**

• Core detector of the CBM experiment

• Momentum resolution,  $\Delta p/p \approx 1.5\%$ 

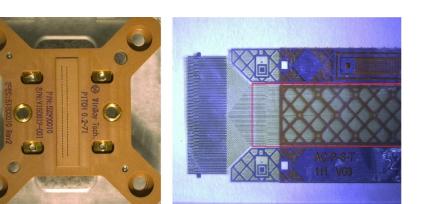
Material Budget ~ 1.5% X<sub>o</sub> per layer

• Self triggering front end electronics

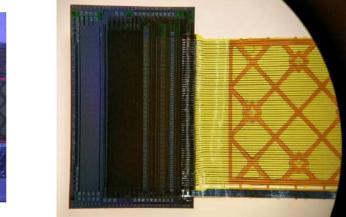
• Track reconstruction efficiency,  $\epsilon \ge 98\%$ 

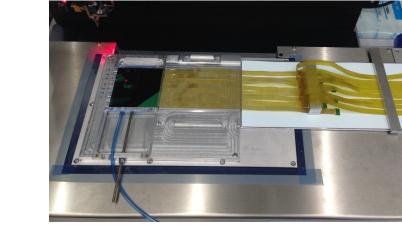
• Located inside dipole magnet

• Hit spatial resolution  $\sim 25 \ \mu m$ 

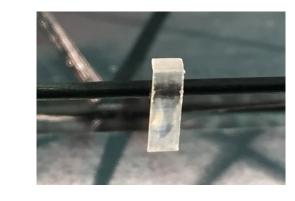


Connectivity test with pogo-pin set-up



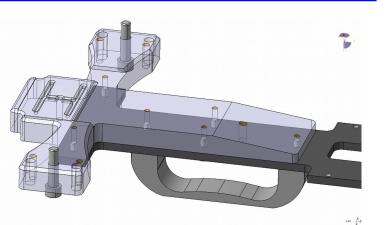


Tab bonding of microcables to Si sensors





L-leg mounting tool holding l-legs L-legs, made of (four l-legs goes in one fixture) Glass fibres



Sensor holding tool

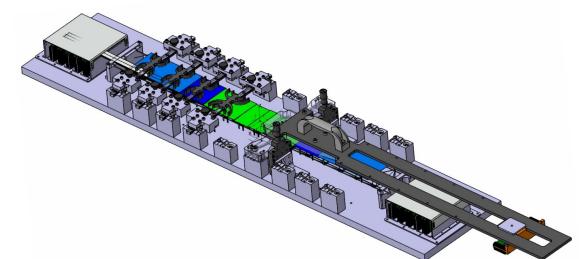




FEBs (Front End

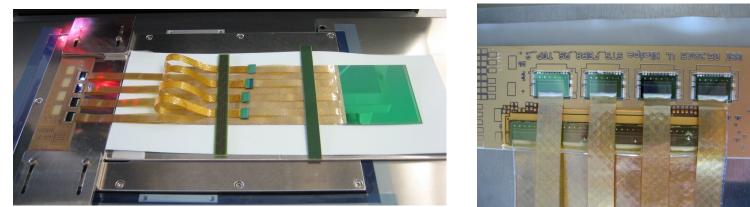
Boards) in

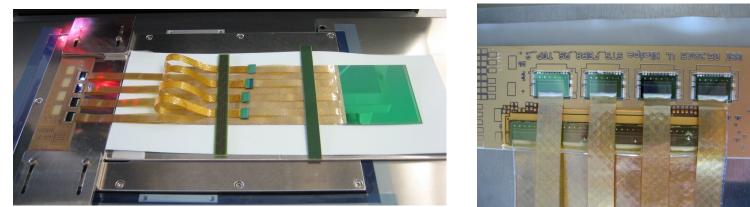
cooling box





microcables to ASIC





# Ladder Assembly

Die and wire-bonding of ASICs to the first row of FEB-8, after quality measurement procedure is repeated for second row



STS-module consists of a double-sided silicon microstrip sensor connected via microcables to two front-end-electronics PCB's



Ladders, Carbon Fibre (CF) support structures

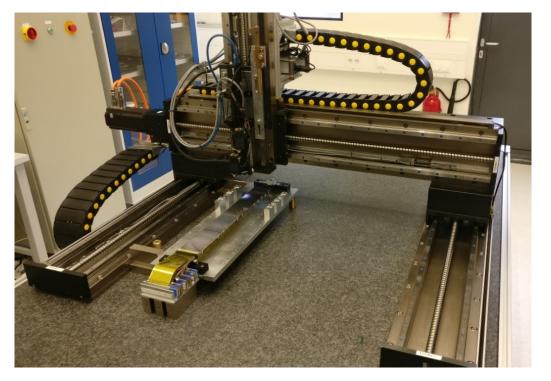


Full size tool to assemble modules on a ladder

- Assembly of CF ladder with 5 non-functional modules using similar tools
- Ensures the feasibility to mount the modules on the tool
- Technique was used to assemble the ladders for m-STS

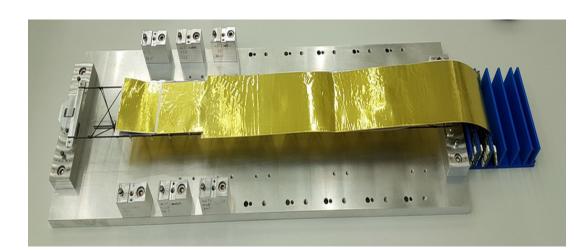
#### **Optical survey & measurement Technique**

- Three-axis measurement instrument (1100 x 800 x 170 mm)
- Equipped with camera & motorized optics
- Overall precision of table taking long term reproducibility of measurement is ± 10 μm
- Goal is to make sure that the sensors position do not deviate from nominal positions by more than 100  $\mu$ m



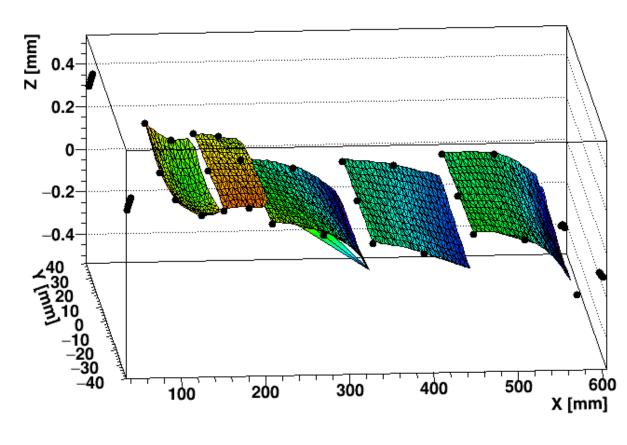
#### **Conclusion and outlook**

- The technique used to assemble the ladder is promising
- Based on the same assembly concept, further ladders will be assembled
- Mounting tools with better precision are in progress for the bulk production
- Measured sensor position will be further used as an input for the track based alignment



Ladder holding two 6 x 6 cm<sup>2</sup> modules covered by shielding

# 



- 3D-position of sensors is determined from alignment marks on surface
- The black dots refer to the alignment marks on the sensors
- Measurement of XY surface is based on pattern recognition technique
- Measurement of height (in Z direction) is based on focusing technique

Nominal module Z position was shifted to zero for all the sensors Z Max-Min: Surface 417 µm Marks 483 µm



#### mSTS

- Full sized half ladders and modules were assembled for the first time
- ASIC configuration was stable
- Integrating prototype detector's modules into a common, freestreaming DAQ
- 13 sensor modules mounted on 5 ladders will be grouped on 2 tracking stations





